



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTN8962TA	Issued	24. February 2022
MA#	MA005709000		
Package	PG-TO263-7-1	Weight*	1533.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.200	0.08	0.08	782	782
chip_2	inorganic material	silicon	7440-21-3	3.738	0.24	0.24	2437	2437
chip_3	inorganic material	silicon	7440-21-3	1.222	0.08	0.08	796	796
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		528	
	non noble metal	copper	7440-50-8	808.613	52.72	52.79	527183	527869
wire	non noble metal	aluminium	7429-90-5	3.809	0.25	0.25	2484	2484
encapsulation	inorganic material	zinc oxide	1314-13-2	5.898	0.38		3846	
	miscellaneous	miscellaneous	-	23.594	1.54		15382	
	plastics	epoxy resin	-	88.476	5.77		57683	
	inorganic material	silicon dioxide	60676-86-0	471.870	30.76	38.45	307641	384552
lead finish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8499	8499
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	139	140
solder	non noble metal	tin	7440-31-5	0.092	0.01		60	
	noble metal	silver	7440-22-4	0.115	0.01		75	
	non noble metal	lead	7439-92-1	4.378	0.29	0.31	2854	2989
glue	plastics	Polyimide	26023-21-2	0.180	0.01	0.01	117	117
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.92	6.93	69245	69335
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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